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transporting said side bars and said substrate film through a manufacturing process; and

removing said side bars after at least a portion of said manufacturing process.

60. (NEW) The method of Claim 59 wherein said act of connecting said side bars comprises substantially aligning a plurality of indexing holes in said side bars with a plurality of indexing holes in said substrate film.

61. (NEW) The method of Claim 59 wherein said act of connecting said side bars substantially aligns said side bars with side rails in said substrate film.

62. (NEW) The method of Claim 59 further comprising the act of connecting cross bars to said substrate film.

63. (NEW) The method of Claim 62 wherein said act of connecting cross bars substantially aligns said cross bars with cross rails in said substrate film.

64. (NEW) The method of Claim 59 further comprising the act of interfacing said substrate film with a plurality of dies.

65. (NEW) A method of processing semiconductor dies comprising:  
forming a plurality of substrate units within a film;  
forming a central cavity in each of said substrate units;  
interfacing said substrate units with a plurality of dies;  
adding support material at selected regions of said film so as to provide enhanced rigidity to said substrate units; and  
removing at least a portion of said support material at the completion of at least a portion of a manufacturing process.

66. (NEW) The method of Claim 65 wherein said act of interfacing said substrate units comprises aligning each said cavity with a respective one of said dies.

67. (NEW) The method of Claim 66 wherein said act of interfacing said substrate units comprises leading wires through each said cavity from a respective one of said dies.

68. (NEW) The method of Claim 67 wherein said act of interfacing said substrate units comprises electrically connecting each of said substrate units with a respective one of said dies.

69. (NEW) The method of Claim 68 wherein said act of interfacing said substrate units comprises connecting said wires between bonding pad surfaces of said substrate units and bonding pad surfaces of said dies.